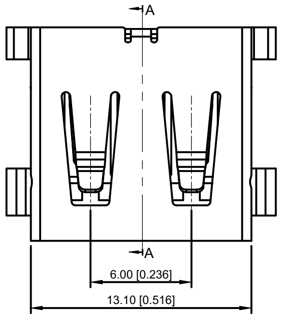
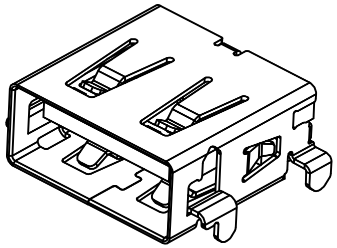
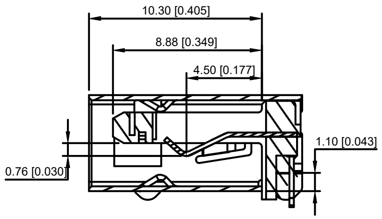






SECTION:A-A

XKB CONNECITITY

XKB CONNECITITY

NOTE:

1.MATERIALSPECIFICATION:
1.HOUSING:PA10T.UL94V-0
2.CONTACTS:COPPER ALLOY(C7025)
3.FRONT SHELL:STAINLESS STEEL(SUS201)

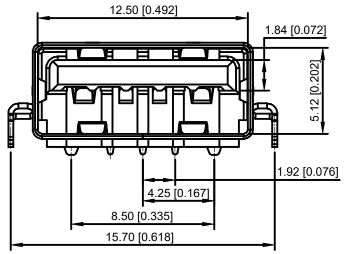
2.PLATING SPECIFICATION:
2-1.TERMINAL:
Ni 50u"MIN.UNDER PLATED OVER ALL.
Au PLATED ON THE FUNCTIONAL AREA OF CONTACT
(GOLD PLATING THICKNESS FOLLOW THE P/N
PLATING SPECIFICATIONS OF THE SOLDER AREA FOLLOW THE P/N
2-2.FRONT SHELL:
Ni 30u"MIN. UNDER PLATED OVER ALL,

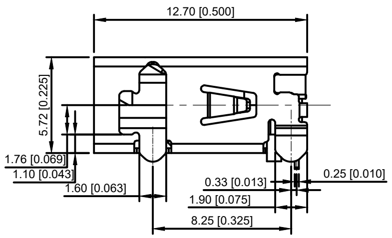
3.MECHANICALPERFORMANCE
3-1.INSERTION FORCE:3.5Kgf MAX
3-2.REMOVAL FORCE:1.02kgf MIN
3-3.DURABILITY:1500 CYCLES.

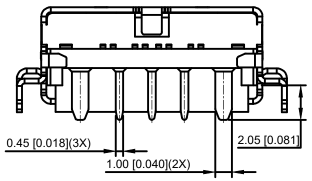
4.ELECTRICAL PERFORMANCE,
4-1.CURRENT RATING:
VBUS & GND PINS: 5A MAX.
OTHER PINS:0.25A MAX.
4-2. LLCR:
VBUS & GND PINS:30mΩ/PIN MAX.
ALL OTHER PINS:50mΩ/PINMAX.
LLCR MAX.CHANGE OF ALL PINS: 10mΩ
4-3.INSULATION RESISTANCE:100MΩ MIN
4-4.DIELECTRIC WITHSTAND VOLTAGE,AC 100V FOR 1 MINUTE.

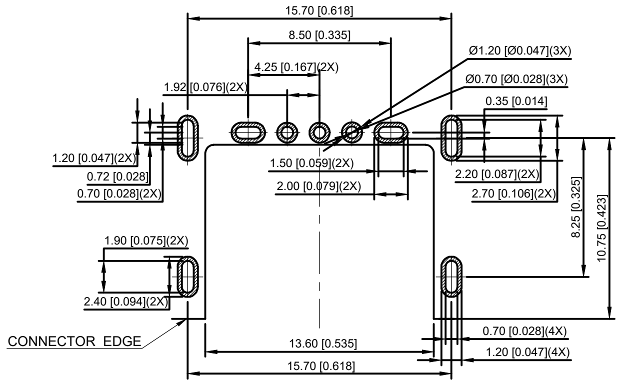
5. ENVIRONMENTALPERFORMANCE:
OPERATING TEMPERATURE:-25℃~+85℃

6.IR REFLOW:
THE PEAK TEMPERATURE ON THE BOARD SHALL
BE MAINTAINED FOR 10 SECONDS AT 260℃.









RECOMMENDED PCB LAYOUT(TOP VIEW)

THICKNESS 1.0±0.10MM:DEFAULT TOLERANCE:±0.05

XKB CONNECITITY

U224-05XN-3GRA035

G:GREEN
B:BLACK
BL:BLUE

1:Au 1U"
5:Au 15U"
6:Au 30U"

1:PBT
2:PA6T
3:PA9T
4:LCP

					ANGLAR	±5°
ΔX					L≤4	±0.2
ΔX					4<L≤16	±0.3
ΔX					16<L≤63	±0.4
MARK	DESCRIPTION	DATE	REVISED	APPROVED	L>63	±0.5
REVISIONS					UNSPECIFIED TOLERANCES	

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DSND		DATE		SCALE: N/A	MODEL TYPE: USB 2.0		
DWN		DATE		VIEW:⊕◁	PART NO.:		
CHKD		DATE		UNIT: mm/in	DWG NO.: U224-05XN-3GRA035		
APPD		DATE		SIZE: A4			
XKB INDUSTRIAL PRECISION CO.,LIMITED					WEIGHT 1.0g	SHEET 1/1	REVISION A0

单击下面可查看定价，库存，交付和生命周期等信息

>>XKB Connectivity(中国星坤)